

## Patent Abstracts of Japan

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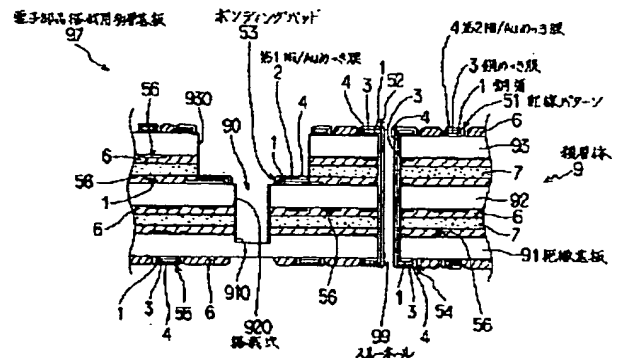
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TITLE : MANUFACTURE OF MULTILAYERED  
SUBSTRATE FOR MOUNTING  
ELECTRONIC COMPONENT



ABSTRACT : PURPOSE: To provide a method for manufacturing a multilayered substrate for mounting electronic components on which a pattern having an excellent corrosion resistance can be easily formed.

CONSTITUTION: After respectively forming wiring patterns 56 and electronic component mounting holes 910, 920, and 930 on a plurality of insulating substrates 91, 92, and 93, a first Ni/Au film is formed by electroless plating on the surface of the exposed sections of the wiring patterns 56, for example, a bonding pad 53 and a laminated body 9 is obtained by piling up the substrates 91, 92, and 93 upon another. Then a through hole 99 is bored through the laminated body 9. After boring the hole 99, the entire surface of the laminated body 9 is plated with Cu 3 including the surface of the Ni/Au film 2 and the inside of the hole 99 and the unnecessary part of the Cu film 3 is etched off. After etching off, a second Ni/Au film 4 is formed on the exposed surfaces of the first Ni/Au film 2 and/or Cu film 3 by electroless plating.

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